

FIG. 1

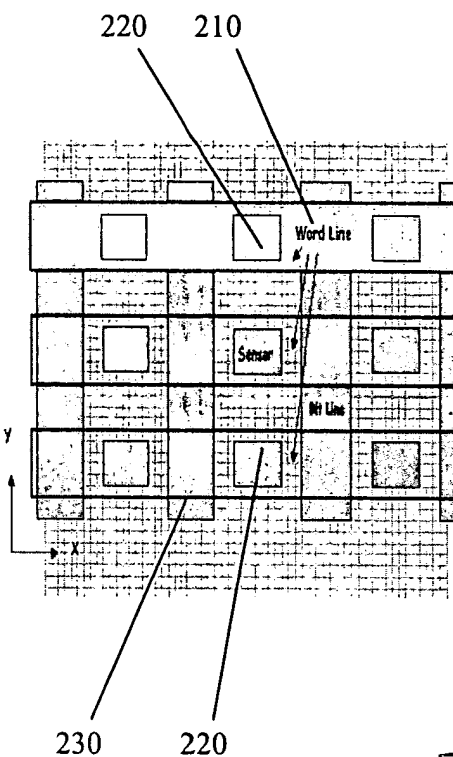
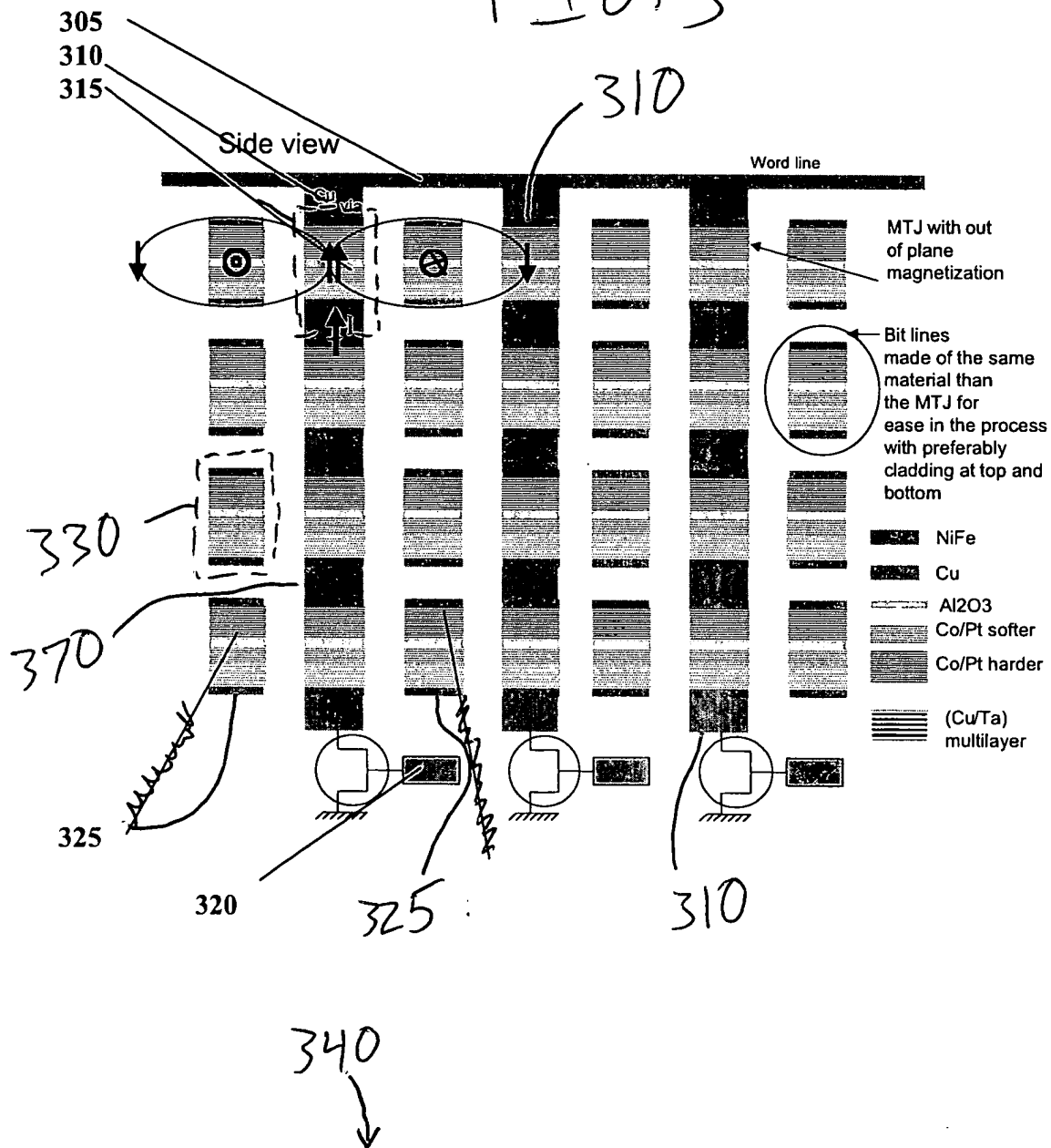


FIG. 2

FIG. 3



345	Cladding layer	NiFe
355	Storage layer	CoPt multilayer 4 repeats
365	Insulating layer	Al2O3
360	Readout layer	CoPt multilayer 2 repeats
350	Conductivity layer	CuTa multilayer
345	Cladding layer	NiFe

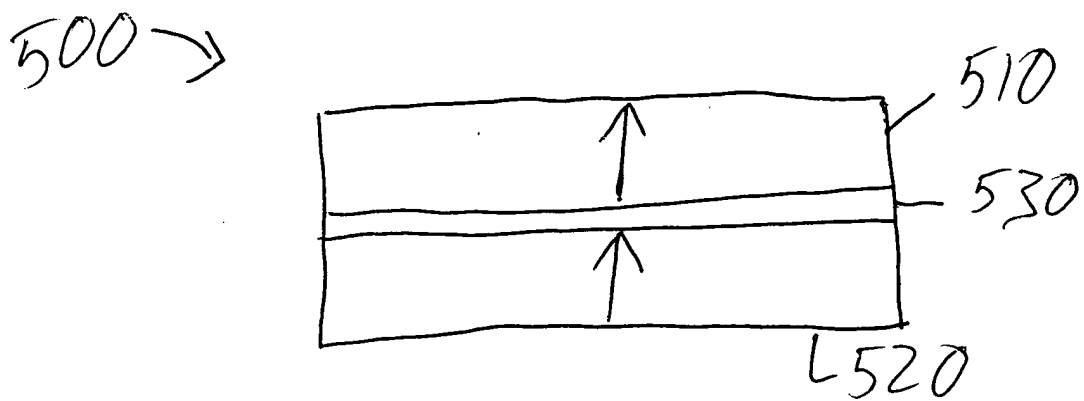
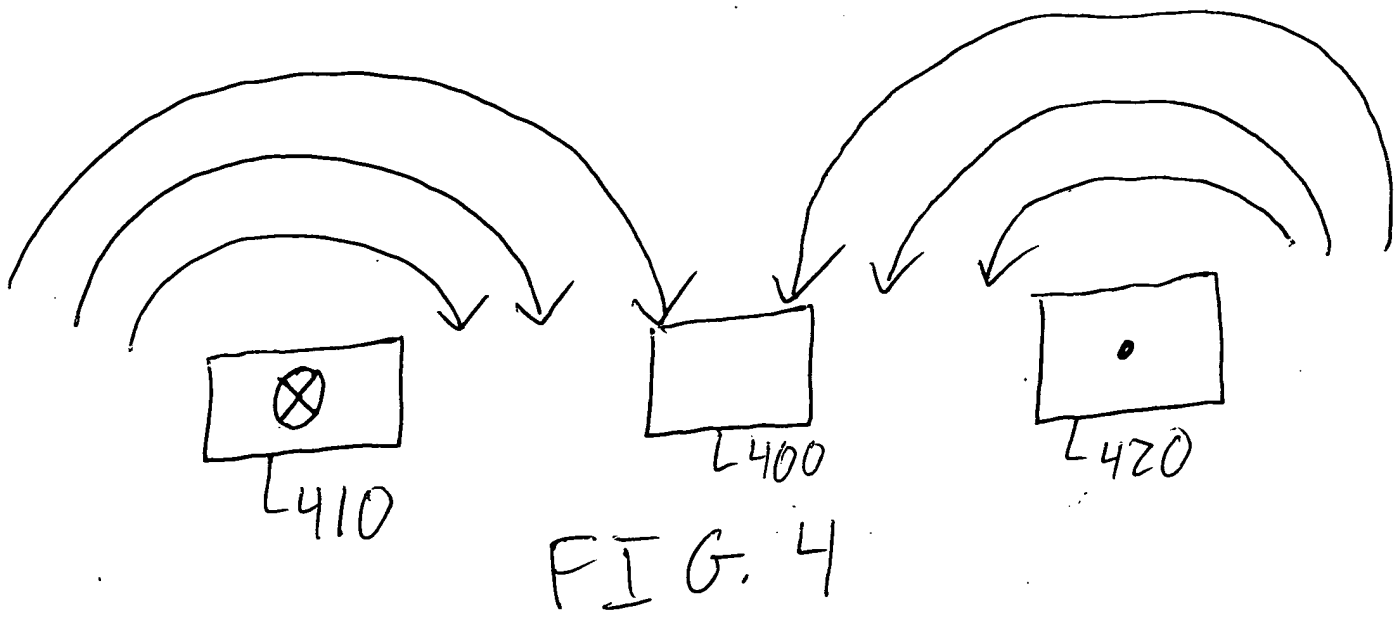


FIG. 5

605

610-1

630-2

610

625

Word line

630-1

615

680

620-1

620

Cu via

MTJ with out of plane magnetization

Bit line made of same material than MTJ stack for ease of the process + NiFe cladding at top only or bottom only

NiFe

Cu

Al₂O₃

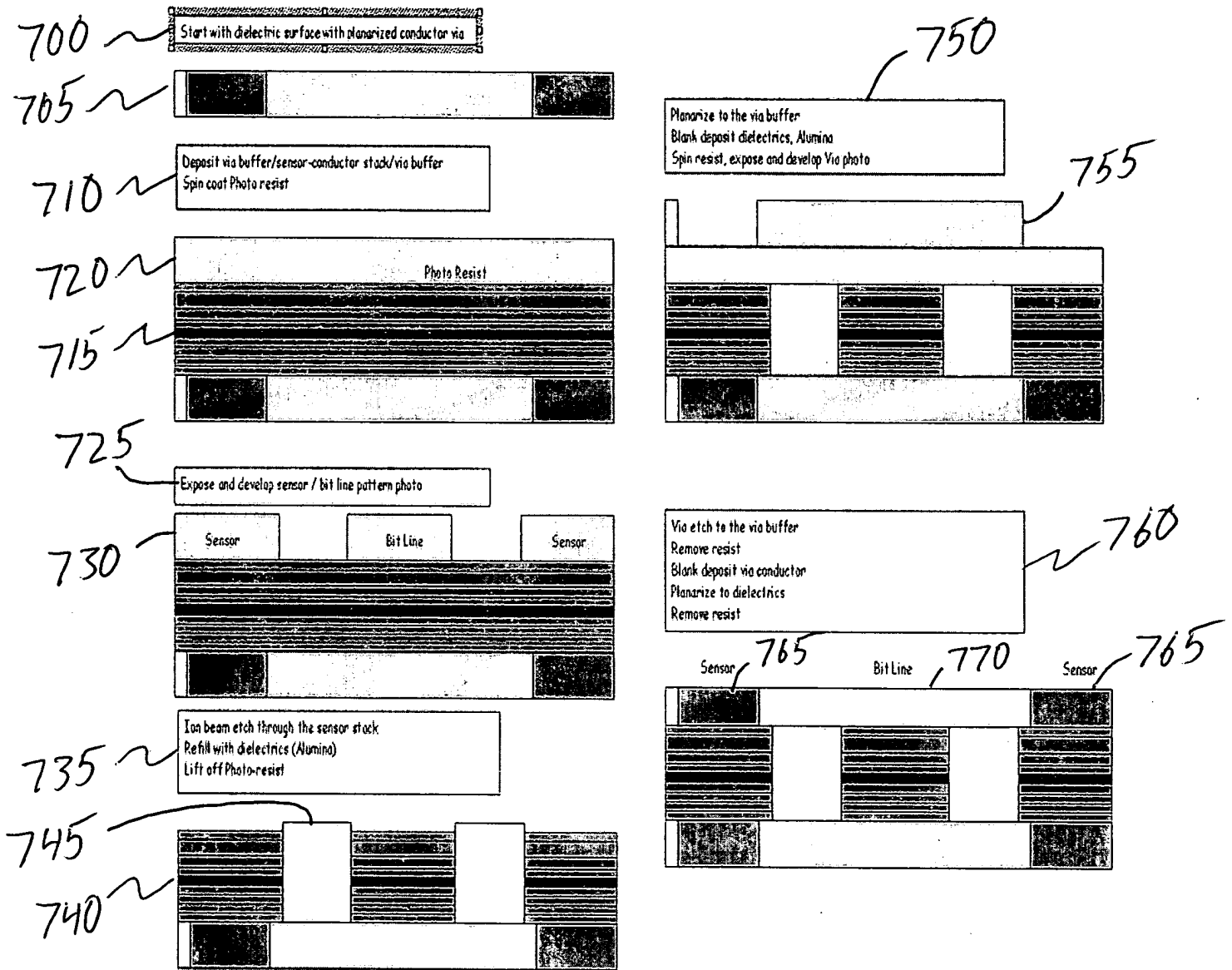
CoFe

IrMn

(Cu/Ta) multilayer

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FIG. 7



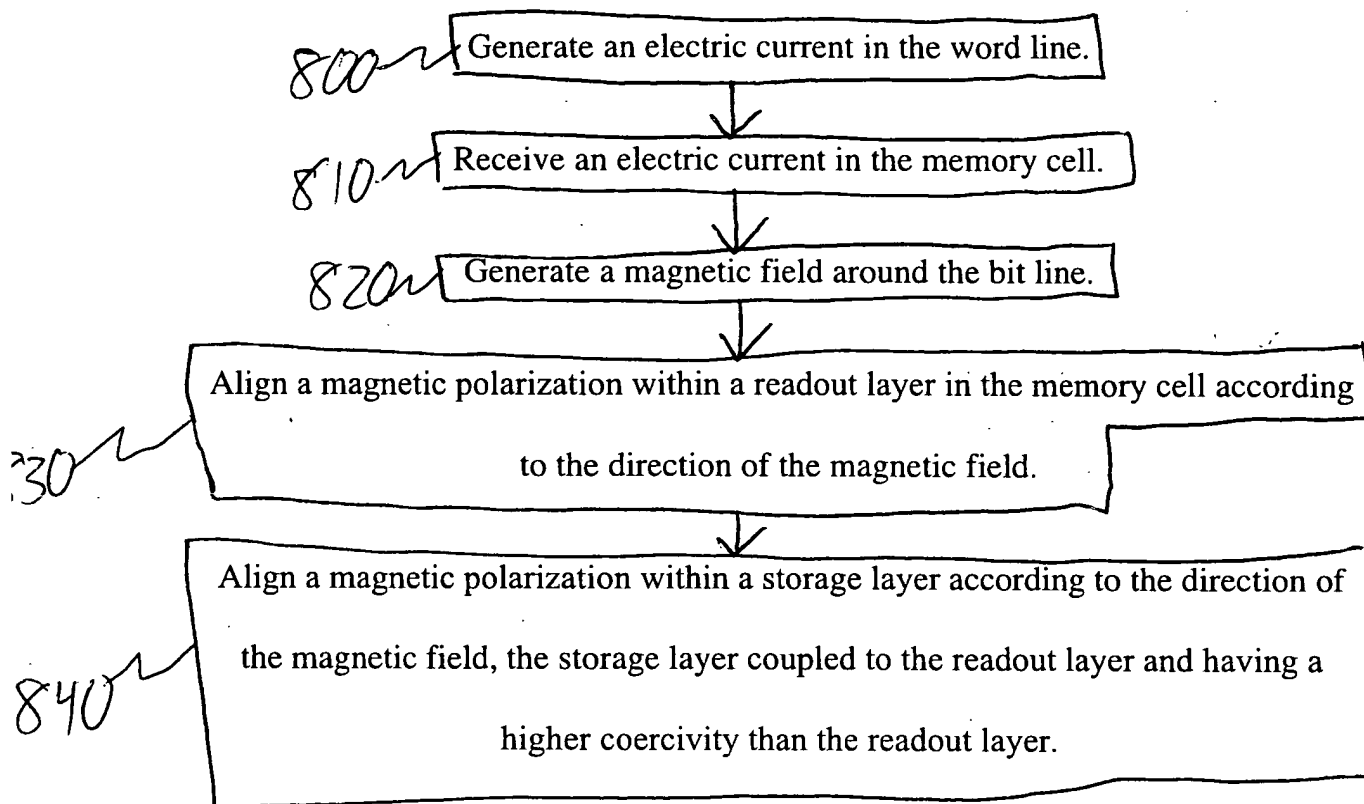


FIG. 8

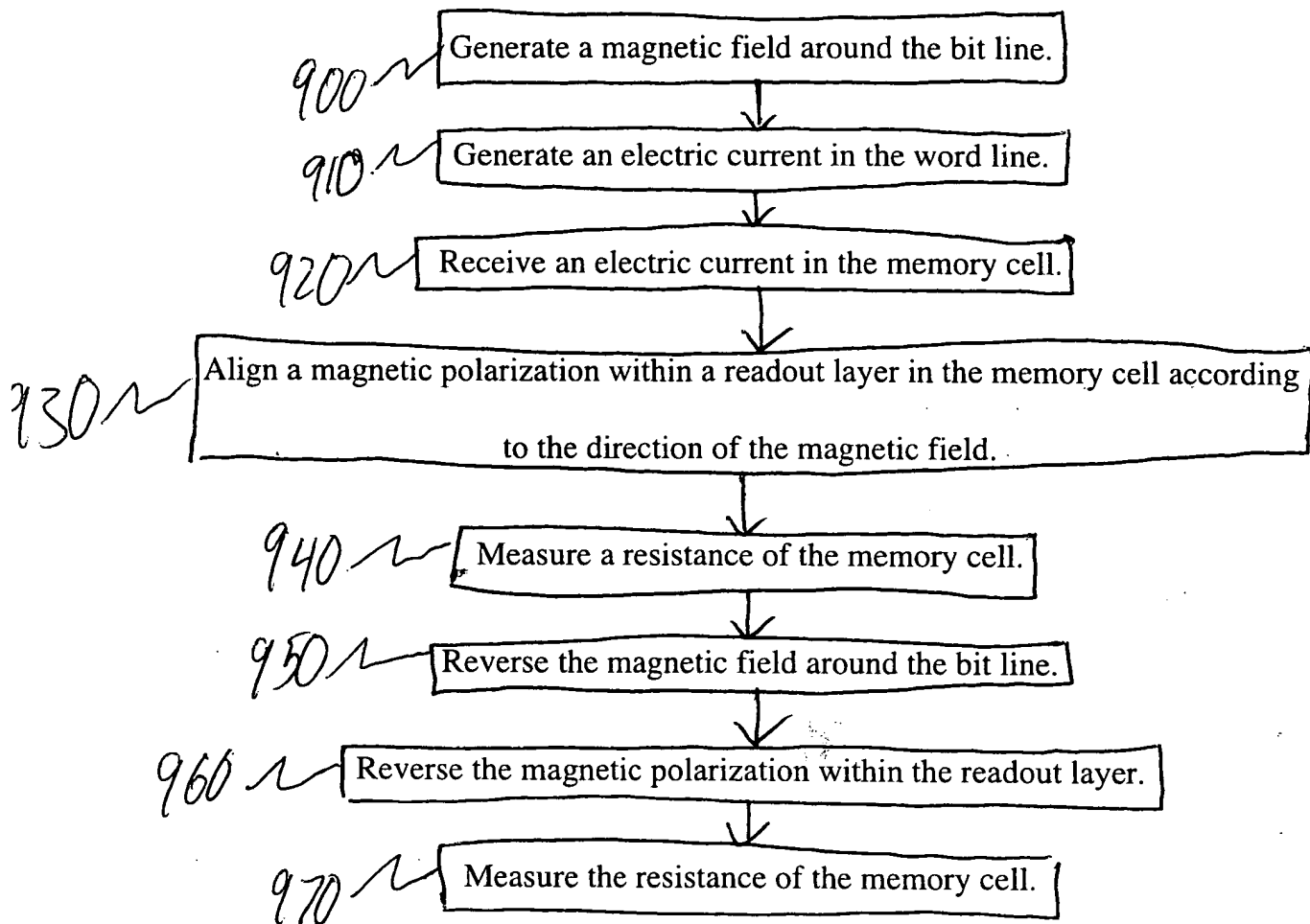


FIG. 9